

NXP Semiconductors

Date: 2014-6-17

Chemical content of PCA9551PW

Typenumber	Package	Package description	Total product weight
PCA9551PW	SOT403-1	TSSOP16	85.62 mg

12NC	Effective	Version	Pb-free soldering			Pb soldering			Number of processing cycles	Assembly site	
			Moisture Sensitivity Level	Peak package temperature	Max time at peak temperature	Moisture Sensitivity Level	Peak package temperature	Max time at peak temperature			
935271692112	17-Sep-10	3	1	260	30 seconds	1	240	20 seconds	3	Bangkok, Thailand	Lead-Free RHF Indicator: D
935271692118	17-Sep-10	3	1	260	30 seconds	1	240	20 seconds	3	Bangkok, Thailand	Lead-Free RHF Indicator: D

Subpart	Material group	Substances	CAS number	Mass(mg)	Mass(%) of Subpart	Mass(%) of Total product	
Die	Doped silicon	Silicon (Si)	7440-21-3	1.53	100	1.79	
		SubTotal			1.53	100	1.79
Wire	Pure metal	Gold (Au)	7440-57-5	0.38	100	0.45	
		SubTotal			0.38	100	0.45
Mould Compound	Polymer	Epoxy resin system		3.4	8.5	3.97	
		Flame retardant	Non hazardous		1.2	3	1.4
		Filler	Misc. Silica compounds ¹	14808-60-7	35.4	88.5	41.35
		SubTotal			40	100	46.72
Adhesive	Polymer	Resin system		0.84	19.9	0.98	
		Filler	Silver (Ag)	7440-22-4	3.36	80.1	3.93
		SubTotal			4.2	100	4.91
Lead Frame Material	Copper alloy	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	1.14	3	1.33	
		Copper (Cu)	7440-50-8	36.86	97	43.05	
		SubTotal			38	100	44.38
Pre-plating	Pure metal layer	Nickel (Ni) - cas no. 7440-02-0	7440-02-0	1.46	97	1.7	
		Gold (Au)	7440-57-5	0.02	1	0.02	
		Palladium (Pd)	7440-05-3	0.03	2	0.04	
		SubTotal			1.51	100	1.76
Total				85.62	100	100	

Note(s):

¹ This is a generic description of the substance used as the actual composition of the substances are either considered proprietary or no official CAS number is available. If a CAS number is given, it is the closest match available.

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